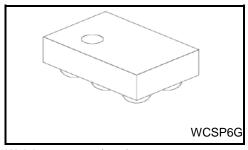
TOSHIBA CMOS Linear Integrated Circuit Silicon Monolithic

# TCK421G

Over Voltage Protection MOSFET Gate Driver IC

# 1. Description

TCK421G series is Over Voltage Protection Gate Driver IC for External N-channel MOSFET. This product support to MOSFET operating in wide voltage line from 2.7 V to 28 V with various Over Voltage Lock Out lineups. And this features low standby current, less than 1  $\mu$ A, built in charge pump circuit and MOSFET gate-source protection circuit. Package is small and thin WCSP6G (1.2 mm x 0.8 mm (typ.), t: 0.35 mm(max)). Thus this is suitable for mobile, wearable system and power management circuit such as load switch application.



Weight : 0.61 mg ( typ.)

## 2. Applications

Load switch circuit for mobile, wearable, and IoT equipment

## 3. Features

- Gate driver for N-channel Common Drain MOSFET
- Gate driver for N-channel Single High side MOSFET
- High maximum input voltage: V<sub>IN max</sub> = 40 V
- Wide input voltage operation: V<sub>IN</sub> = 2.7 to 28 V
- Gate-Source protection circuit
- Over Voltage Lock Out : V<sub>IN\_OVLO</sub> = 23.26 V typ
- Under Voltage Lock Out : VIN\_UVLO = 2.0 V typ
- Built in Charge pump circuit: Gate source voltage V<sub>GS</sub> = 10 V typ
- Low standby current :  $I_{Q(OFF)} = 0.9 \ \mu A \ max \ at \ V_{IN} = 12 \ V$

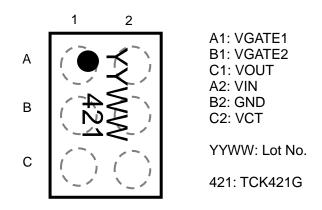
# 4. Absolute Maximum Ratings (Note)

Characteristics	Symbol	Rating	Unit
Input voltage	VIN	-0.3 to 40	V
Output voltage	Vout	-0.3 to 40	V
Control voltage	Vст	-0.3 to 6	V
Ourput GATE voltage	VGATE1,2	-0.3 to 40	V
Power dissipation	PD	800 (Note 1)	mW
Operating temperature range	T <sub>opr</sub>	-40 to 85	°C
Junction temperature	Tj	150	°C
Storage temperature	T <sub>stg</sub>	-55 to 150	°C

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings. Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

Note1: Rating at mounting on a board: FR4 board. (  $40 \text{ mm} \times 40 \text{ mm} \times 1.6 \text{ mm}$ , Cu 4 layer )

## 5. Top Marking, Pin Assignment (top view)



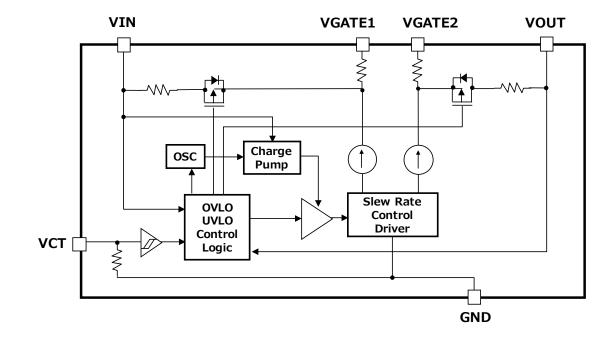
# 6. Operating Ranges

Characteristics	Symbol	Min.	Тур.	Max.	Unit
Input operation voltage	VIN_opr	2.7	_	28	V
CONTROL High-level input voltage	Vih	1.2	_	5.5	V
CONTROL Low-level input voltage	VIL	_	_	0.4	V

# 7. List of Products Number, OVLO and VGS

Product number	OVLO threshold, falling typ (V)	External MOSFET Gate- Source voltage (Control ON) typ (V)
TCK421G	23.26	10

# 8. Block Diagram



# 9. PIN Description

PIN	Name	Description
A1	VGATE1	Gate Driver Output for Gate 1 Or OPEN state (Non connection) for Single MOSFET use case
B1	VGATE2	Gate Driver Output for Gate 2
C1	VOUT	Monitoring Output voltage Connecting Output (Source 2) of Common Drain MOSFET Or Connecting Output (Source) of single MOSFET use case
A2	VIN	Input power supply voltage Connecting Output (Source 1) of Common Drain MOSFET Or Connecting Output (Drain) of single MOSFET use case
B2	GND	Ground
C2	VCT	Mode control input terminal VCT=High turn the external MOSFETs OFF

# 10. Operation Table

## $2.7V \le V_{IN} \le 28 \text{ V} \text{ (Ta} = -40 \text{ to } 85^{\circ}\text{C}\text{)}$

VCT	VGATE1, VGATE2
High	Driver ON mode
Open	Driver OFF mode
Low	

## **11. Electrical Characteristics**

## 11.1. DC Characteristics (Ta = -40 to 85°C)

Characteristics	Symbol	Ta = 25°C		Ta = 25°C		Ta = -40 to 85°C (Note 2)		Unit
			Min.	Тур.	Max.	Min	Max	
VIN UVLO threshold, $V_{OUT}$ falling	VIN_UVLO			2.0	_	_	2.5	V
VIN UVLO hysteresis	VIN_UVhyst		_	0.2		_		V
VIN OVLO threshold, Vout falling	VIN_OVLO			23.26	_	22.34	24.05	V
VIN OVLO hysteresis	VIN_OVhyst		—	0.12	—	_		V
		$V_{CT}$ : High, $V_{IN}$ = 2.7 V	_	140		_	200	μΑ
		V <sub>CT</sub> : High, V <sub>IN</sub> = 4 V	_	130			420	μA
Input quiescent current		V <sub>CT</sub> : High, V <sub>IN</sub> = 5 V		140			300	μA
(ON state)	IQ(ON)	V <sub>CT</sub> : High, V <sub>IN</sub> = 9 V		170		_	460	μA
		V <sub>CT</sub> : High, V <sub>IN</sub> = 12 V	_	185		_	490	μA
		V <sub>CT</sub> : High, V <sub>IN</sub> = 20 V	_	220		_	560	μA
		V <sub>CT</sub> : Low, V <sub>IN</sub> = 2.7 V	_	0.14	_	_	0.3	μA
		Vct: Low, VIN = 4 V		0.25		_	0.4	μA
Standby current		Vct: Low, VIN = 5 V		0.28	_	_	0.5	μA
(OFF state)	lq(off)	V <sub>CT</sub> : Low, V <sub>IN</sub> = 9 V		0.42			0.7	μA
		V <sub>CT</sub> : Low, V <sub>IN</sub> = 12 V	_	0.52		_	0.9	μA
		V <sub>CT</sub> : Low, V <sub>IN</sub> = 20 V		0.80		_	1.3	μA
GATE Drive voltage		VIN = 2.7 V	_	9.2	—	8	10	V
(VGATE1-VIN)	VGS	V <sub>IN</sub> = 12 V	_	10	—	9	11	V
(VGATE2-VIN)	(Note 3)	VIN = 20 V	_	10	_	9	11	V
Control pull down resistance	RCT	Vct = 5 V	_	550	_	_	_	kΩ

Note 2: This parameter is warranted by design

Note 3:  $V_{IN}$  is stable power supply condition

## 11.2. AC Characteristics (Ta = 25°C, V<sub>IN</sub> = 5 V, C<sub>GATE1,2</sub> (Note 4) = 4000 pF)

Characteristics	Symbol	Test Condition (Figure 2,3)	Min.	Тур.	Max.	Unit
VGS ON time	tON	Initial startup time VGATE2 – VOUT = 1 V after VCT = High, IOUT = 0 mA	_	2.9	_	ms
V <sub>GS</sub> OFF time	tOFF	$V_{GATE2} - V_{OUT} = 1 V$ , after $V_{CT} = Low$ , $I_{OUT} = 0 mA$		52	_	μS

#### 11.3. AC Characteristics (Ta = 25°C, VIN = 20 V, CGATE1,2 (Note 4) = 4000 pF)

Characteristics	Symbol	Test Condition (Figure 2,3)		Тур.	Max.	Unit
VGS ON time	tON	Initial startup time V <sub>GATE2</sub> – V <sub>OUT</sub> = 1 V after V <sub>CT</sub> = High, I <sub>OUT</sub> = 0 mA	_	2.9	_	ms
V <sub>GS</sub> OFF time	tOFF	$V_{GATE2} - V_{OUT} = 1 V$ , after $V_{CT} = Low$ , $I_{OUT} = 0 mA$	_	36	_	μS

#### 11.4. AC Characteristics (Ta = 25°C, C<sub>GATE1,2</sub> (Note 4) = 4000 pF)

Characteristics	Symbol	Test Condition (Figure 4,5)	Min.	Тур.	Max.	Unit
OVLO VGS turn OFF time	tOVP	$V_{IN} > V_{IN\_OVLO MAX}$ , $V_{IN rising} = 2 V/\mu s$ $V_{GS}$ typ to $V_{GS}$ ( $V_{GATE2}$ - $V_{OUT}$ ) = 1 V $I_{OUT} = 0 mA$		34	_	μS

Note 4: CGATE1 and CGATE2 are input capacitance connected to each VGATE1 and VGATE2 instead of external MOSFET

## 11.5. Timing Chart

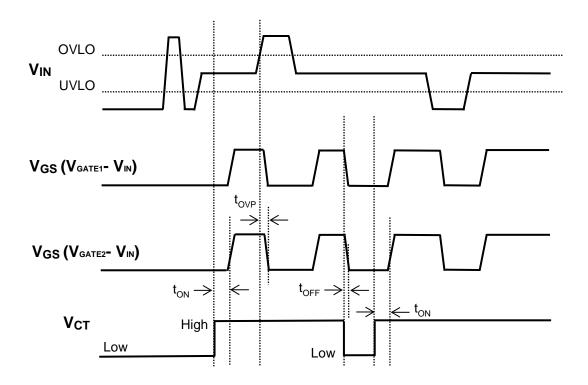
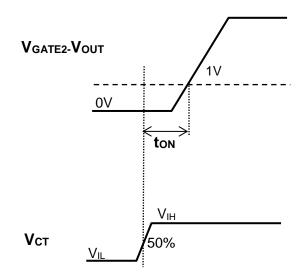
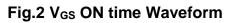


Fig.1 ton, toff, tovp

## Switching Waveform and Test circuit





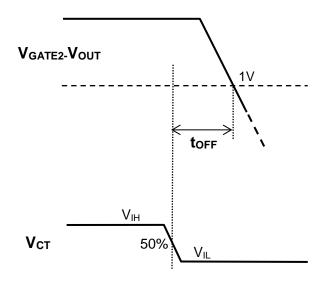
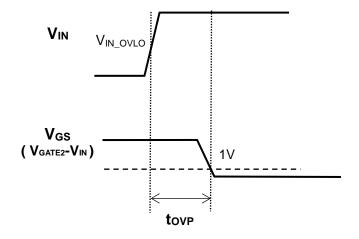


Fig.3 V<sub>GS</sub> OFF time Waveform







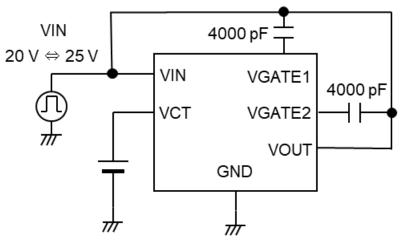
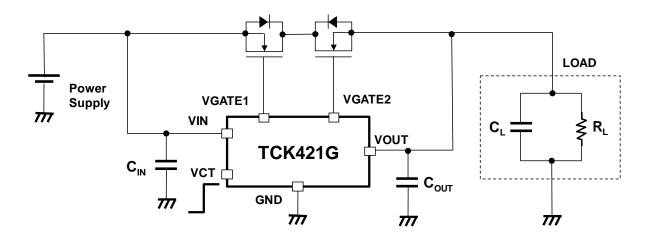


Fig.5 tovp test circuit

## 12. Application Note

#### 12.1. Common Drain Connection N-channel MOSFET circuit example



#### 1) Input and Output capacitor

An input capacitor ( $C_{IN}$ ) and an output capacitor ( $C_{OUT}$ ) are recommended for the stable operation. And it is effective to reduce voltage overshoot or undershoot due to sharp changes in output current and also for improved stability of the power supply. When used, place  $C_{IN}$  and  $C_{OUT}$  as close to  $V_{IN}$  pin to improve stability of the power supply.

#### 2) VCT pin

VCT pin is pull down connection to GND. VCT High level voltage must be under 5.5V  $V_{IH}$  max.

#### 3) VGATE1,2 pin and VOUT pin

VGATE1 pin is connected to Gate of VIN side MOSFET. VGATE2 pin is connected to Gate of VOUT side MOSFET. VOUT pin is connected to Source of VOUT side MOSFET. When the gate driver IC turns off state, VGATE1 terminal voltage is close to VIN voltage dropped by parasitic diode forward voltage. This circuit works to protect over voltage for VIN side MOSFET Gate-Source terminal. VOUT terminal works to protect VOUT side MOSFET as same circuit.

#### 4) Turn on recovery time after Over Voltage Lock Out (OVLO)

Once VIN is in normal voltage range after OVLO, the turn on recovery time is similar V<sub>GS</sub> ON time (t<sub>ON</sub>).

#### 5) Under Voltage Lock Out (UVLO) and Over Voltage Lock Out (OVLO)

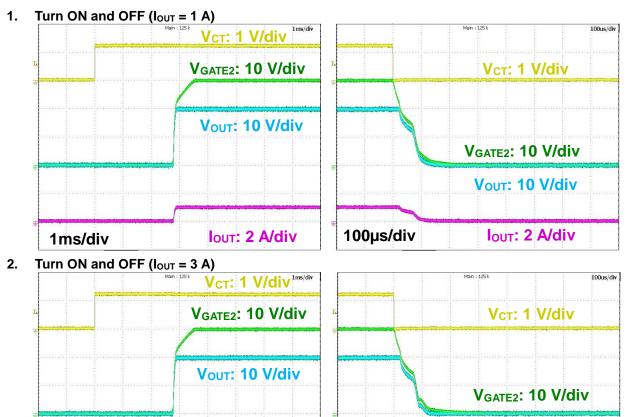
UVLO and OVLO are designed in these products, but these are not designed to constantly ensure the suppression of the gate driver IC and external MOSFETs within operation limits. Depending on the condition during actual usage, it could affect the electrical characteristic specification and reliability. To select external MOSFETs, please consider enough electrical design margin. When using these products, please read through and understand the concept of dissipation for absolute maximum ratings from the above mention or our 'Semiconductor Reliability Handbook'. Then use these products under absolute maximum ratings in any condition. Furthermore, Toshiba recommends inserting failsafe system into the design.

#### Common Drain Connection N-channel MOSFET Switching Waveform

#### Typical switching waveforms with TOSHIBA MOSFETs

OVP Gate	MOSFET	Test conditions			
Driver IC	Part Number	Description	Turn ON and OFF	Over Voltage Lock Out	
		Single N-channel MOSFET			
	TPN1R603PL	$V_{DSS}$ : 30 V, $V_{GSS}$ : ± 20 V	V <sub>IN</sub> = 20 V	V <sub>IN</sub> = 20 V ⇔ 25 V	
	TENTROUSEL	$R_{DS(ON)}$ : 1.2 m $\Omega$ typ at $V_{GS}$ = 10 V	I <sub>OUT</sub> = 1 A, 3 A	$I_{OUT} = 1 \text{ A}$	
TCK421G		Package: TSON Advance	$C_{IN} = 1 \ \mu F$	$C_{IN} = 1 \ \mu F$	
10K4210		Single N-channel MOSFET	$C_{OUT} = 1 \ \mu F$	$C_{OUT} = 1 \ \mu F$	
	TPHR6503PL1	V <sub>DSS</sub> : 30 V, V <sub>GSS</sub> : ± 20 V	$V_{CT} = 0 V \Leftrightarrow 1.2 V$	V <sub>CT</sub> = 1.2 V	
	IPHRODUSPLI	$R_{DS(ON)}$ : 0.41 m $\Omega$ typ at $V_{GS}$ = 10 V	Ta = 25 °C	Ta = 25 °C	
		Package: SOP Advance(N)			

#### TCK421G + TPN1R603PL x 2pcs



100µs/div

1ms/div

lout: 2 A/div

VIN: 5 V/div

VGATE2: 10 V/div

Vout: 10 V/div

lout: 2 A/div

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100µs/div

1ms/div

**Over Voltage Lock Out** 

3.

1ms/div

Vout: 10 V/div

lout: 2 A/div

VIN: 5 V/div

VGATE2: 10 V/div

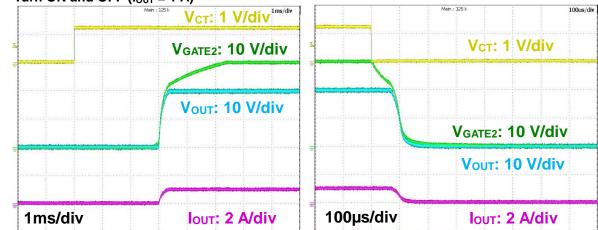
Vout: 10 V/div

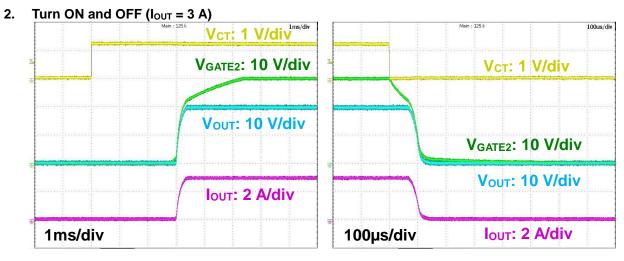
lout: 2 A/div

Main : 125 k

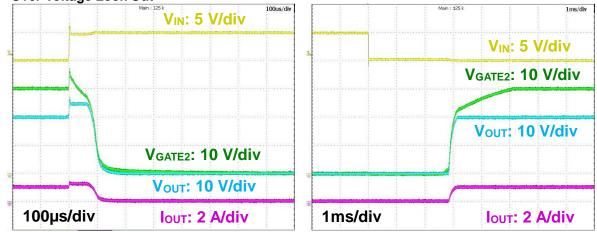
#### TCK421G + TPHR6503PL1 x 2pcs

1. Turn ON and OFF ( $I_{OUT} = 1 A$ )

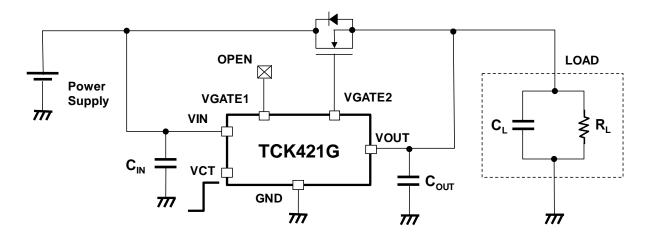




3. Over Voltage Lock Out



### 12.2. Single N-channel MOSFET circuit example



#### 1) Input and Output capacitor

An input capacitor ( $C_{IN}$ ) and an output capacitor ( $C_{OUT}$ ) are recommended for the stable operation. And it is effective to reduce voltage overshoot or undershoot due to sharp changes in output current and also for improved stability of the power supply. When used, place  $C_{IN}$  and  $C_{OUT}$  as close to  $V_{IN}$  pin to improve stability of the power supply.

#### 2) VCT pin

VCT pin is pull down connection to GND. VCT High level voltage must be under 5.5V  $V_{\text{IH}}$  max.

#### 3) VGATE1,2 pin and VOUT pin

VGATE1 pin is OPEN state/Non connection. VGATE2 pin is connected to Gate of MOSFET. VOUT pin is connected to Source of MOSFET. When the gate driver IC turns off state, VGATE2 terminal voltage is close to VOUT voltage dropped by parasitic diode forward voltage. This circuit works to protect over voltage for MOSFET Gate-Source terminal.

#### 4) Turn on recovery time after Over Voltage Lock Out

Once VIN is in normal voltage range after OVLO, the turn on recovery time is similar V<sub>GS</sub> ON time (t<sub>ON</sub>).

#### 5) Under Voltage Lock Out (UVLO) and Over Voltage Lock Out (OVLO)

UVLO and OVLO are designed in these products, but these are not designed to constantly ensure the suppression of the gate driver IC and external MOSFETs within operation limits. Depending on the condition during actual usage, it could affect the electrical characteristic specification and reliability. To select external MOSFETs, please consider enough electrical design margin. When using these products, please read through and understand the concept of dissipation for absolute maximum ratings from the above mention or our 'Semiconductor Reliability Handbook'. Then use these products under absolute maximum ratings in any condition. Furthermore, Toshiba recommends inserting failsafe system into the design.

### Single N-channel MOSFET Switching Waveform

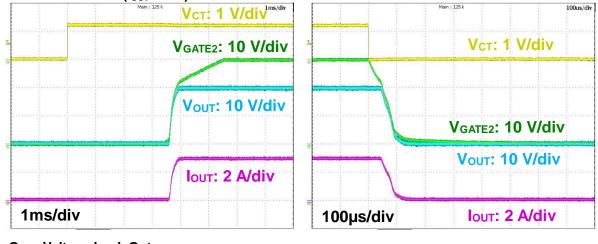
#### Typical switching waveforms with TOSHIBA MOSFETs

OVP Gate	MOSFET		Test conditions			
Driver IC	Part Number	Description	Turn ON and OFF	Over Voltage Lock Out		
			V <sub>IN</sub> = 20 V	$V_{IN} = 20 V \Leftrightarrow 25 V$		
		Single N-channel MOSFET	I <sub>OUT</sub> = 1 A, 3 A	I <sub>OUT</sub> = 1 A		
TCK421G	TPHR6503PL1	V <sub>DSS</sub> : 30 V, V <sub>GSS</sub> : ± 20 V	$C_{IN} = 1 \ \mu F$	$C_{IN} = 1 \ \mu F$		
TCK421G	TPHRODUSPLI	$R_{DS(ON)}$ : 0.41 m $\Omega$ typ at $V_{GS}$ = 10 V	$C_{OUT} = 1 \ \mu F$	$C_{OUT} = 1 \ \mu F$		
		Package: SOP Advance(N)	V <sub>CT</sub> = 0 V ⇔ 1.2 V	V <sub>CT</sub> = 1.2 V		
			Ta = 25 °C	Ta = 25 °C		

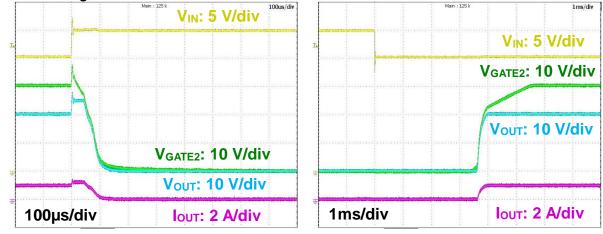
#### TCK421G + TPHR6503PL1

## 1. Turn ON and OFF (l<sub>out</sub> = 1 A) Men:25k Vcr: 1 V/div VGATE2: 10 V/div Vout: 10 V/div 100us/div Vout: 10 V/div Vout: 10 V/div Vout: 10 V/div Vout: 10 V/div Vout: 2 A/div Vout: 2 A/div

2. Turn ON and OFF (I<sub>OUT</sub> = 3 A)



3. Over Voltage Lock Out



85°C

25°C

-40°C

85°C

25°C

-40°C

200

40

30

 $V_{GATE2}$  vs.  $V_{IN}$ 

20 Input Voltage (V)

 $V_{GS}(V_{GATE2}-V_{IN})$  vs.  $I_{GATE}$ 

40

VGATE2 Voltage (V) 0 00 00

0

12

10

8

6

4

2

0

0

50

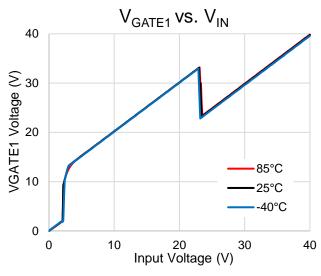
VGATE2 - Source Voltage (V)

0

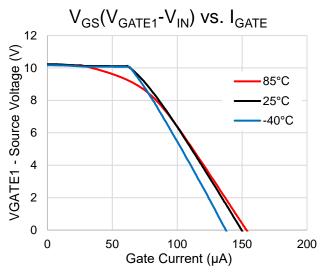
10

# **13. Representative Typical Characteristics**

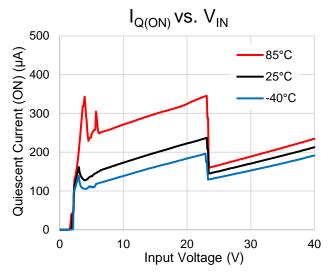
## 13.1. Gate voltage vs. Input voltage

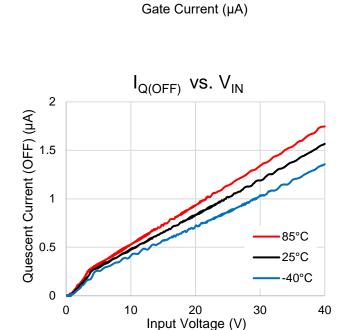












100

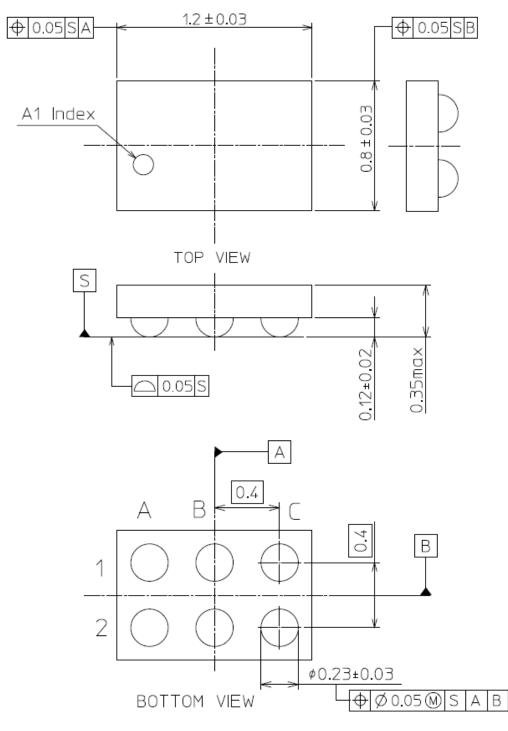
150



## 14. Package Information

## WCSP6G

Unit: mm

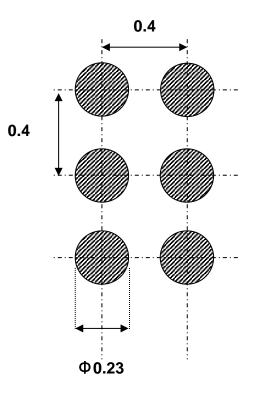


Weight: 0.61 mg (Typ.)

# 15. Land pattern dimensions for reference only

#### WCSP6G

Unit: mm



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